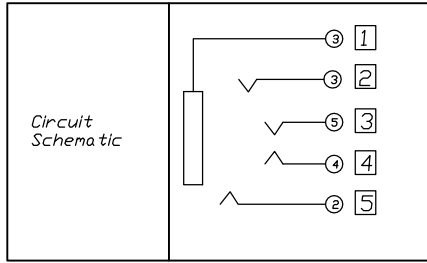
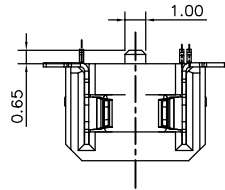
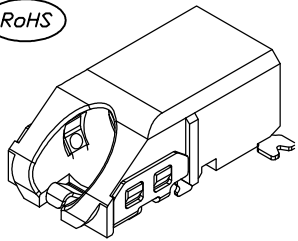
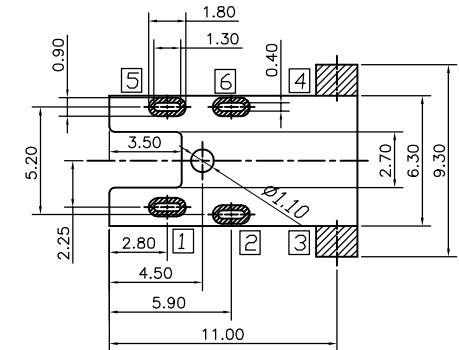


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

RoHS



□ TERMINAL NO
○ ITEM NO



PCB LAYOUT(TOP VIEW) 1:05

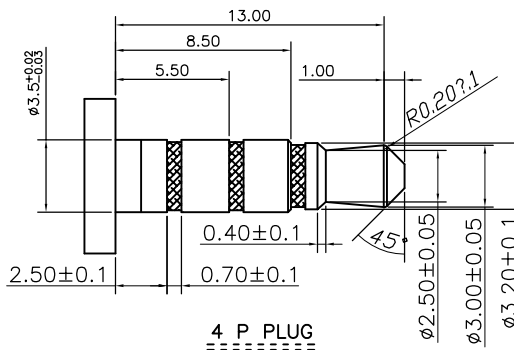
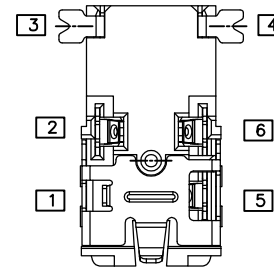
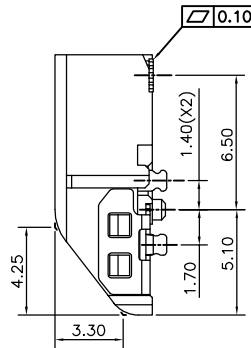
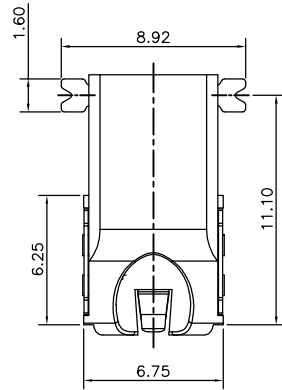
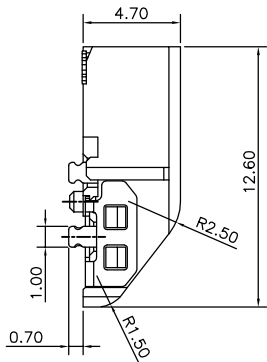
NATING:

1.0 RATING:

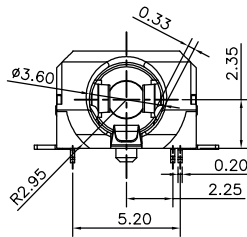
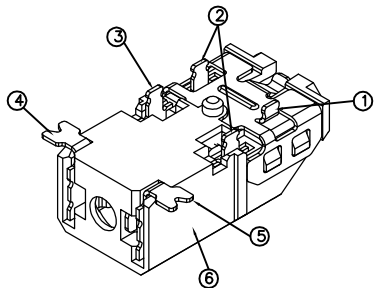
- 1.1 VOLTAGE:12 VAC
- 1.2 CURRENT: 1 AMPERE MAXIMUM PER CONTACT 30° cT-RISE
- 1.3 TEMPERATURE:-25° cTO+85° c
- 2.0 CONTACT RESISTANCE:
- 2.1 CONTACT RESISTANCE:INITIAL 50mΩ MAX.
- 2.2 INSULATION RESISTANCE:100M MIN
- 2.3 DIELECTIC WITHSTANDING VOLTAGE:500 VAC AT SEA LEVEL

WLPJF9-06 3 X X 0 008

PLATING: 1-G/F
2-Au 3u"
5-Au 15u"
6-Au 30u"
COLOUR: A-Black



4 P PLUG



NO.	ITEM	Q'TY	DESCRIPTION	FINISH
⑥	HOUSING	1	LCP ,BLACK	UL94V-0
⑤	CONTACT 4	1	copper alloy	PLATED Au
④	CONTACT 4	1	copper alloy	PLATED Au
③	CONTACT 3	1	copper alloy	PLATED Au
②	CONTACT 2	2	copper alloy	PLATED Au
①	CONTACT 1	1	copper alloy	PLATED Au

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES	SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	
A0	NEW RELEASE	21.01.13	LINEAR 0.0±0.35	APPROVED	Wang_jr	21.01.13	WLPJF9-063XX0008	ENDE05	
			ANGLES X°REF±6°	DESIGNER	Ding_bo	21.01.13	TITLE:	 WanLian Teconology Co., Ltd	
			UNIT: mm 0.00±0.25	DRAWN	Du_jian	21.01.13	PHONE JACK $\phi 3.5$ SMT+DIP TYPE CONN		REV: A0
			SIZE: A4 0.000±0.10						SHEET: 1/1